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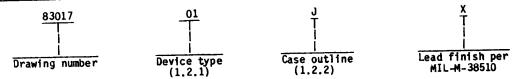
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1	SCOP	F

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type

O1

Generic number

Circuit

4-line to 16-line decoder/demultiplexer

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	case outline
Ј К 3	D-3 (24-lead, 1/2" x 1 1/4") dual-in-line package F-6 (24-lead, 3/8" x 5/8") flat package C-4 (28-terminal, .450" x .450"), square chip carrier package

Casa sutling

1.3 Absolute maximum ratings.

1.4 Recommended operating conditions.

- 1/ Must withstand the added PD due to short-circuit test (e.g., I_{OS}).
- $\frac{2}{}$ When a thermal resistance for this case is specified in MIL-4-38510, appendix C, that value shall supersede the value specified herein.

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2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by contractors in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.2 Truth table. The truth table shall be as specified on figure 2.
 - 3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.
 - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table $\bar{1}$ and apply over the full recommended case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-833 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

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	TABLE I.	Electrical performance charac	teristics - Continued	•		
Test	Symbol	Conditions -55°C < T _C < +125° unless otherwise spe	Group A subgroups	Min	Max	Unit
High-level output voltage	V _{OH}	$ V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -0.4 \text{ W}$ $ V_{IH} = 2.0 \text{ V} \qquad V_{IL} = 0.7 \text{ V}$	nA 1, 2, 3	2.5		٧
Low-level output voltage	V _{OL}	V _{CC} = 4.5 V,	1, 2, 3		0.4	٧
Input clamp voltage	AIC	V _{CC} = 4.5 V, I _{IN} = -18 m	1		-1.5	٧
Low-level input current	IIL	V _{CC} = 5.5 V, V _{IN} = 0.4 V	1, 2, 3		-400	μA
High-level input current	I IH1	V _{CC} = 5.5 V,	1, 2, 3		20	μΑ
Input current at max input voltage	I _{IH2}	V _{CC} = 5.5 V, V _{IN} = 7 V	1, 2, 3		0.1	mA.
High-level output current	гон		1, 2, 3		-0.4	mA I
Low-level output current	IOL		1, 2, 3		4	mA
Short-circuit output current	Ios	V _{CC} = 5.5 V, V _{OUT} = 0.0	v <u>1</u> / 1, 2, 3	-15	 -100 	mA
Supply current	I _{CC}	V _{CC} = 5.5 V, V _{IN} = GND	2/ 1, 2, 3		14	mA

See footnotes at end of table.

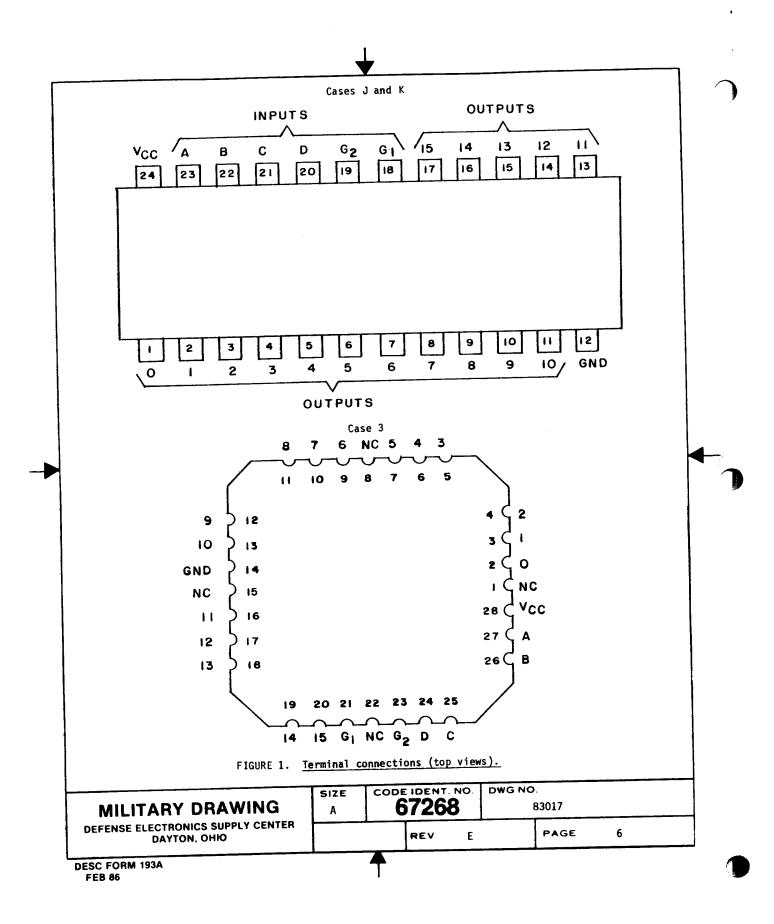
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TA	BLE I.	Electrical performance characteristic	s - Continued	•		
Test	 Symbol 	Conditions Conditions -55°C < T _C < +125°C unless otherwise specified	Group A subgroups	Min	Max 	Unit
Propagation delay time A, B, C, or D inputs through 3 levels of logic	t _{PLH1}	$V_{CC} = 5.0 \text{ V},$ $R_L = 2 \text{ k}\Omega \pm 5\%,$ $C_L = 50 \text{ pF} \pm 10\%$	9, 10, 11		 53 	ns
	tpHL1	T -	9, 10, 11		50	ns
Propagation delay time from either strobe input	t _{PLH2}	† 	9, 10, 11		46 	ns
	t _{PHL2}	† 	9, 10, 11		 50 	ns

Not more than one output should be shorted at one time, and the duration of the short-circuit condition should not exceed one second.

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²/ I_{CC} is measured with all inputs grounded and all outputs open.

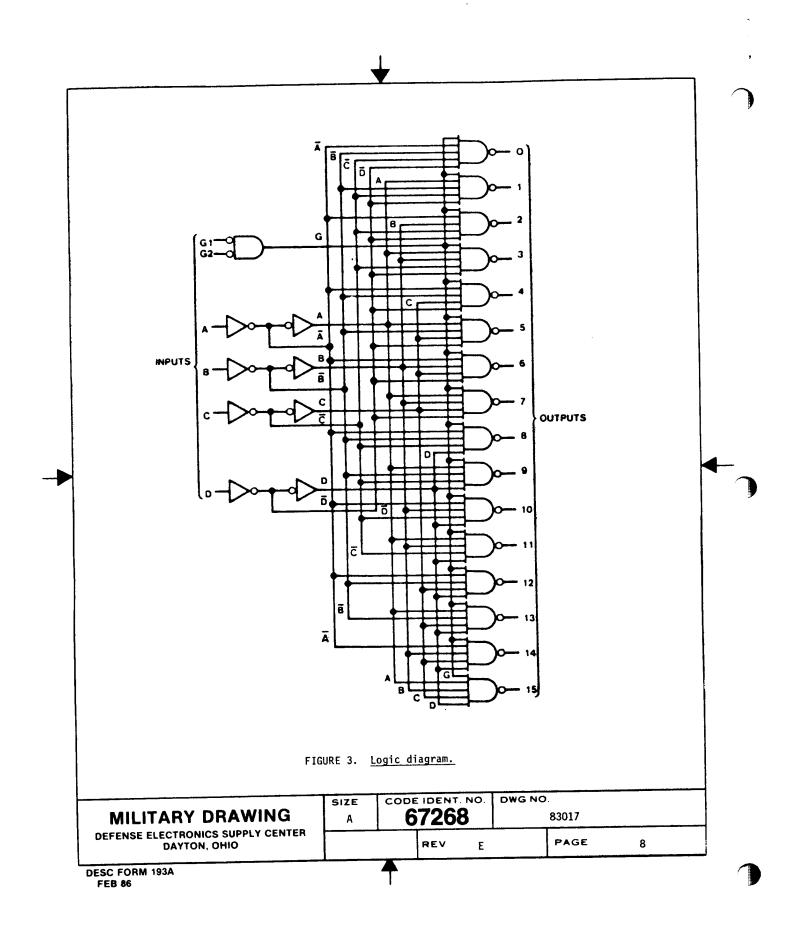


		Inpu	its										Outp	outs							
G1	G2	D	С	В	Α	0	1_	2	3	4	5	6	7_	8_	9	10	11	12	13	14	15
L	L	L	L	L	L	L	н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н
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Н	Н	X	Х	Х	Х	H	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н.	Н

H = High Level, L = Low Level, X = Don't Care

FIGURE 2. Truth table.

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- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test (method 1015 of MIL-STD-883).
 - (1) Test condition A, B, C, or D, using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125$ °C, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 4, 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 7 tests shall verify the truth table.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)	
Interim electrical parameters (method 5004)		
 Final electrical test parameters (method 5004) 	1*, 2, 3, 9	
Group A test requirements (method 5005)	1, 2, 3, 7, 9	
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3	
Additional electrical subgroups for group C periodic inspections	10, 11**	

- * PDA applies to subgroup 1.
- ** Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.
- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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6.4 Approved sources of supply: Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5) has been submitted to DESC-ESC.

 Military drawing part number	Vendor CAGE number	Yendor similar part number <u>1</u> /
 8301701JX 	27014 18324	DM54LS154FJ/8838 54LS154/BJA
8301 701K X	2/	
83017013X	2/	

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

2/ Not available from an approved source of supply.

Vendor CAGE number

Vendor name and address

27014

National Semiconductor Corporation 2900 Semiconductor Drive Santa Clara, CA 95051

18324

Signetics Corporation 4130 South Market Court Sacramento, CA 95834

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